

REMARKS

This paper responds to the Office Action mailed on November 2, 2005.

Claims 19 and 20 are amended, claims 1-12 are canceled without prejudice or disclaimer, and claims 51-61 are added; as a result, claims 13-61 are now pending in this application with claims 19-25 and claims 51-61 currently being examined. Applicant reserves the right to reintroduce claims 1-12 in a divisional application at a later date. The amendments to the claims are fully supported by the specification as originally filed. No new matter is introduced. Applicant respectfully requests reconsideration of the above-identified application in view of the amendments above and the remarks that follow.

The amendments to claim 19 find support in the specification, for example, on page 10, lines 20-21. Support for claims 51-61 may be found in the specification, for example, at page 9, line 8 – page 11, line 30. No new matter is introduced.

In the Specification

The specification is amended to update the status of the parent application from which the instant application claims priority. No new matter is introduced.

Claim Objections

Claim 20 was objected to because of informalities.

Claim 20 is amended. Applicant respectfully requests withdrawal of these objections of claim 20, and reconsideration and allowance of this claim.

First §103 Rejection of the Claims

Claims 19 and 21-25 were rejected under 35 U.S.C. § 103(a) as being unpatentable over Gillespie (U.S. 5,898,858) in view of Capote et al. (U.S. 6,121,689).

Applicant reserves the right to swear behind Capote et al. (hereafter Capote) at a later date.

Applicant cannot find in the combination of Gillespie and Capote a teaching or a suggestion of an electronic system including a pre-packaged flip chip having an adhesive layer covering a first side of a semiconductor device, where the adhesive layer has an array of

openings and has a chamfer at each of the openings as recited in claim 19, as amended. Therefore, since the combination of Gillespie and Capote does not teach or suggest all the elements of claim 19, Applicant submits that claim 19 is patentable over Gillespie in view of Capote.

Claims 21-25 depend on claim 19. Thus, Applicant submits that claims 21-25 are patentable over Gillespie in view of Capote for at least the reasons stated above with respect to claim 19.

Applicant respectfully requests withdrawal of these rejections of claims 19 and 21-25, and reconsideration and allowance of these claims.

Second §103 Rejection of the Claims

Claim 20 was rejected under 35 U.S.C. § 103(a) as being unpatentable over Gillespie in view of Capote et al. and further in view of Toyosawa et al. (U.S. 6,337,257).

Applicant reserves the right to swear behind Toyosawa et al. (hereafter Toyosawa) at a later date.

Applicant cannot find in the combination of Gillespie, Capote, and Toyosawa, as proffered in the Office Action, a teaching or a suggestion of an electronic system including a pre-packaged flip chip having an adhesive layer covering a first side of a semiconductor device, where the adhesive layer has an array of openings and has a chamfer at each of the openings as recited in claim 19. Therefore, since the combination of Gillespie, Capote, and Toyosawa does not teach or suggest all the elements of claim 19, Applicant submits that claim 19 is patentable over the combination of Gillespie, Capote, and Toyosawa. Claim 20 depends on claim 19. Thus, Applicant submits that claim 20 is patentable over Gillespie in view of Capote in further view of Toyosawa for at least the reasons stated above with respect to claim 19.

Applicant respectfully requests withdrawal of these rejections of claim 20, and reconsideration and allowance of this claim.

New Claims

Applicant submits that newly added claims 51-61 depend from patentable claim 19. Applicant respectfully requests consideration and allowance of claims 51-61.

AMENDMENT AND RESPONSE UNDER 37 CFR § 1.111

Serial Number: 10/723,474

Filing Date: November 26, 2003

Title: ELECTRONIC APPARATUS HAVING AN ADHESIVE LAYER FROM WAFER LEVEL PACKAGING

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Dkt: 303.601US2

CONCLUSION

Applicant respectfully submits that the claims are in condition for allowance, and notification to that effect is earnestly requested. The Examiner is invited to telephone Applicant's attorney at (612) 371-2157 to facilitate prosecution of this application.

If necessary, please charge any additional fees or credit overpayment to Deposit Account No. 19-0743.

Respectfully submitted,

SUAN J. BOON

By his Representatives,

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.
P.O. Box 2938
Minneapolis, MN 55402
(612) 371-2157

Date 2 February 2006

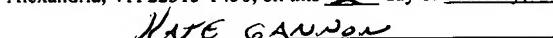
By _____

David R. Cochran
Reg. No. 46,632



CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: Mail Stop Amendment, Commissioner of Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on this 2 day of February, 2006.

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